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## PRE-STANDARD

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**Qualification and performance specification of permanent solder mask and flexible cover materials**

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# INTERNATIONAL ELECTROTECHNICAL COMMISSION

## QUALIFICATION AND PERFORMANCE SPECIFICATION OF PERMANENT SOLDER MASK AND FLEXIBLE COVER MATERIALS

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## Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Supersedes IPC-SM-840D

April 2007

*A standard developed by IPC*

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IPC-SM-840E

# Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Developed by the Solder Mask Performance Task Group (5-33B) of the Cleaning and Coating Committee (5-30) and the Covercoat Materials Task Group (D-13B) of the Flexible Circuits Committee (D-10) of IPC

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**Contact:**

IPC  
3000 Lakeside Drive, Suite 309S  
Bannockburn, Illinois  
60015-1249  
Tel 847 615.7100  
Fax 847 615.7105

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---

### Flexible Circuits Committee

Chair  
Douglas O. Pauls  
Rockwell Collins

Vice-Chair  
Debora L. Obitz  
Trace Laboratories - East

### Solder Mask Performance Task Group

Chair  
David A. Vaughan  
Taiyo America, Inc.

Vice-Chair  
Douglas O. Pauls  
Rockwell Collins

### Covercoat Materials Task Group

Chair  
Steve A. Musante  
Raytheon Missile Systems

### Technical Liaisons of the IPC Board of Directors

Peter Bigelow  
IMI Inc.

Sammy Yi  
Aptina Imaging Corporation

---

### Solder Mask Performance Task Group and Covercoat Materials Task Group

Gregory Bartlett, Teledyne Printed Circuit Technologies	Russell Griffith, Flexible Circuits Inc.	Roger J. Miedico, Raytheon Company
John Bauer, Rockwell Collins	Michael J. Jawitz, Boeing Satellite Development Center	William Ortloff, Raytheon Company
Michael Beauchesne, Amphenol Printed Circuits, Inc.	Nick Koop, Minco Products Inc.	Robert Sheldon, Pioneer Circuits Inc.
Joshua Civiello, Defense Supply Center Columbus	Karin LaBerge, Microtek Laboratories	Terry Shepler, Electro-Materials, Inc.
Mark Finstad, Flexible Circuit Technologies, Inc.	John Leschisin, Minco Products Inc.	Douglas J. Sober, Kaneka Texas Corporation
Thomas F. Gardeski, Gemini Sciences	Anne Lomonte, Draeger Medical Systems, Inc.	Brent Sweitzer, Multek Flexible Circuits, Inc.
Marc Goudreau, Vulcan Flex Circuit Corporation	Duane B. Mahnke, DBMahnke Consulting	Steve J. Vetter, NSWC Crane
	Thomas McCarthy, Taconic Advanced Dielectric Division	Clark F. Webster, ALL Flex LLC
		Miou Yamaoka, Meiko Electronics Co. Ltd.



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# Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

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## 1 SCOPE AND DESIGNATION

**1.1 Scope** This specification **shall** define the criteria for and method of obtaining the maximum information about and confidence in cured permanent solder mask and cover material under evaluation with the minimum of test redundancy.

This specification **shall** establish the requirements for:

- The evaluation of solder mask and cover materials
- The conformance of solder mask and cover material properties
- The qualification of the solder mask and cover material via the appropriate test substrate
- The qualification assessment of the solder mask and cover material in conjunction with the production printed board process